

Jacob, Rebecca (ASRC)

From: STIC-ILL
Sent: Friday, April 11, 2003 6:36 AM
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From: Umez-Eronini, Lynette
Sent: Thursday, April 10, 2003 5:45 PM
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LL Ordering Information:

Art Unit or Location: 1765

Telephone Number: 306-9074

Application Number or Other Order Identifier: PCT/US02/01983

Below is the suggested reference ordering information that STIC needs to locate each reference. You may choose to cut and paste a citation containing this information, rather than filling in the details manually.

Author (if known): Hayashi, Y. et al.

Article Title: A New Abrasive-Free, Chemical -Mechanical-Polishing for Aluminium Metallization of ULSI Devices

Journal or Book Title: International Electron Devices Meeting Technical Digest

Pages if a Journal: 976-978

Volume and Issue if a Journal:

Year of Publication: 1992

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(abrasive free polishing)

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1 Improved Cu abrasive-free polishing at 0.13 /spl mu/m manufacturing and beyond

Yamada, Y.; Konishi, N.; Ohashi, N.; Kimura, T.;

Interconnect Technology Conference, 2002. Proceedings of the IEEE 2002 International , 2002

Page(s): 108 -110

[\[Abstract\]](#) [\[PDF Full-Text \(290 KB\)\]](#) **IEEE CNF**

2 A 7 level metallization with Cu damascene process using newly developed abrasive free polishing

Yamaguchi, H.; Ohashi, N.; Imai, T.; Torii, K.; Noguchi, J.; Fujiwara, T.; Saito, T.; Owada, N.; Homma, Y.; Kondo, S.; Hinode, K.;

Interconnect Technology Conference, 2000. Proceedings of the IEEE 2000 International , 2000

Page(s): 264 -266

[\[Abstract\]](#) [\[PDF Full-Text \(480 KB\)\]](#) **IEEE CNF**

3 Improved Cu CMP process for 0.13 μm node multilevel metallization

Ohashi, N.; Yamada, Y.; Konishi, N.; Maruyama, H.; Oshima, T.; Yamaguchi, H.; Satoh, A.;

Interconnect Technology Conference, 2001. Proceedings of the IEEE 2001 International , 2001

Page(s): 140 -142

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